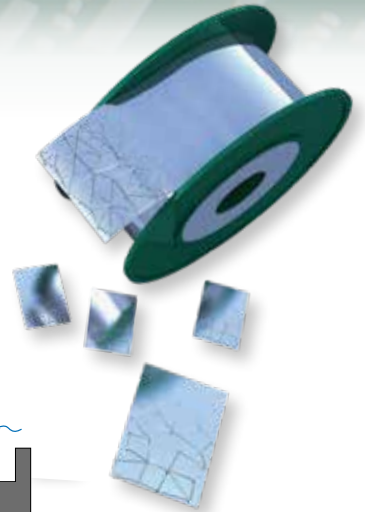


Power Electronics Materials

Reliability Delivered

A variety of industries are requiring more and more power from power electronics. As this trend continues, it is critical that we continue to research and develop materials that can meet power electronics' thermal, voiding, and all-around reliability needs.

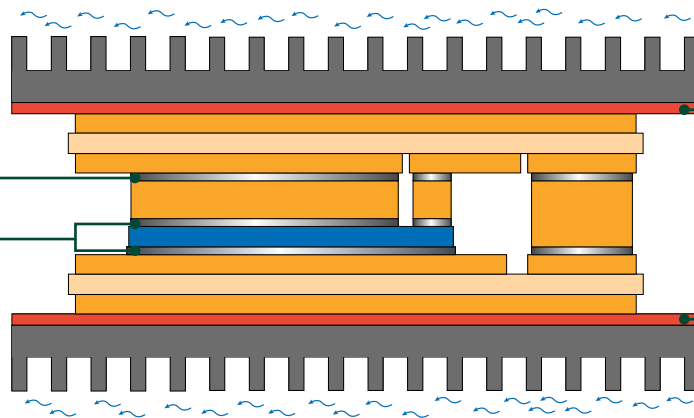


Substrate-/Spacer-Attach Solutions

- Uniform bondline
- Low-voiding

Die-Attach Solutions

- Uniform bondline
- Dependable standoff heights



Thermal Solutions

- Low thermal resistance
- No pump-out or bake-out

Proven Bondline Control

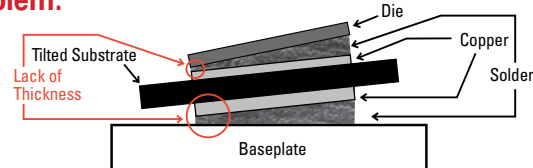
InFORMS®

Preforms and Ribbon*

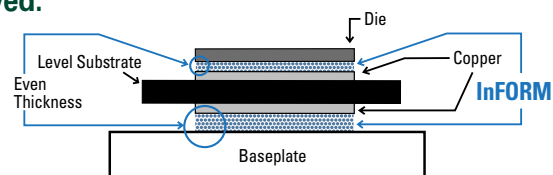
- >2X increase in reliability (-55/+150°C) passes 3,500 thermal cycles
- Most uniform bondline control
- Eliminates costly wire bond trimming process
- Improved strength and dependable standoff heights
- Low-voiding
- Lowest cost of ownership

*Patent pending

Problem:



Solved:



Contact our engineers: askus@indium.com

Learn more: www.indium.com

From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

Power Electronics Materials

Reliability Delivered

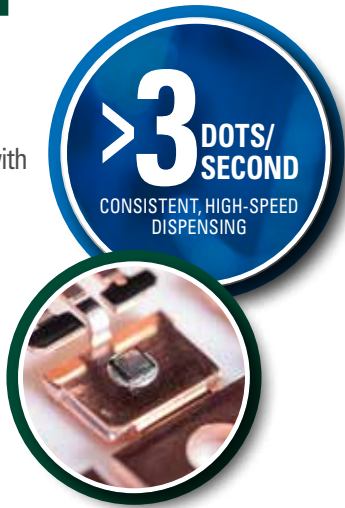
Proven Fast Sintering

QuickSinter® **NEW**

Silver Sintering Paste

- Excellent joint strength
- Pressureless sintering solution with pressurized sintering capabilities
- Controllable bondline thickness from 30–70µm
- Versatile sintering profiles
- Voiding: <1%*
- Porosity: <30%*

*Average on most application runs



High-Performance

Metal Thermal Interface Solutions

No pump-out or bake-out

- Heat-Spring®
- HSP
- HSMF
- Liquid metal
- m2TIM™

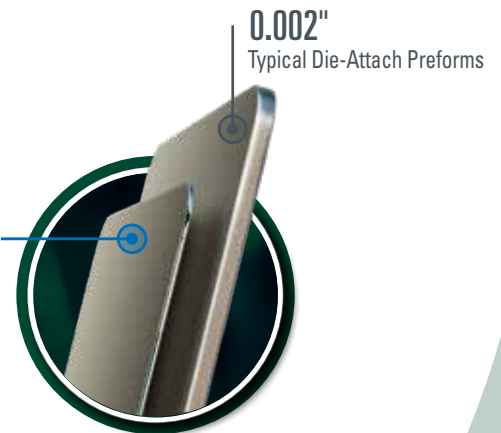


Premium 80Au20Sn

AuLTRA™ ThInFORMS™ **NEW**

- Gold-tin preforms for die-attach applications
- Available in ultra-thin dimensions—0.00035" (0.00889mm)
- Improve thermal transfer and overall operational efficiency
- Reduce voiding, solder volume, and wicking up the die

0.00035"
AuLTRA™ ThInFORMS™



Other Available Products for Power Semiconductors

- LV1000
- Indium3.2HF Solder Paste
- Solder preforms
- and more...

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